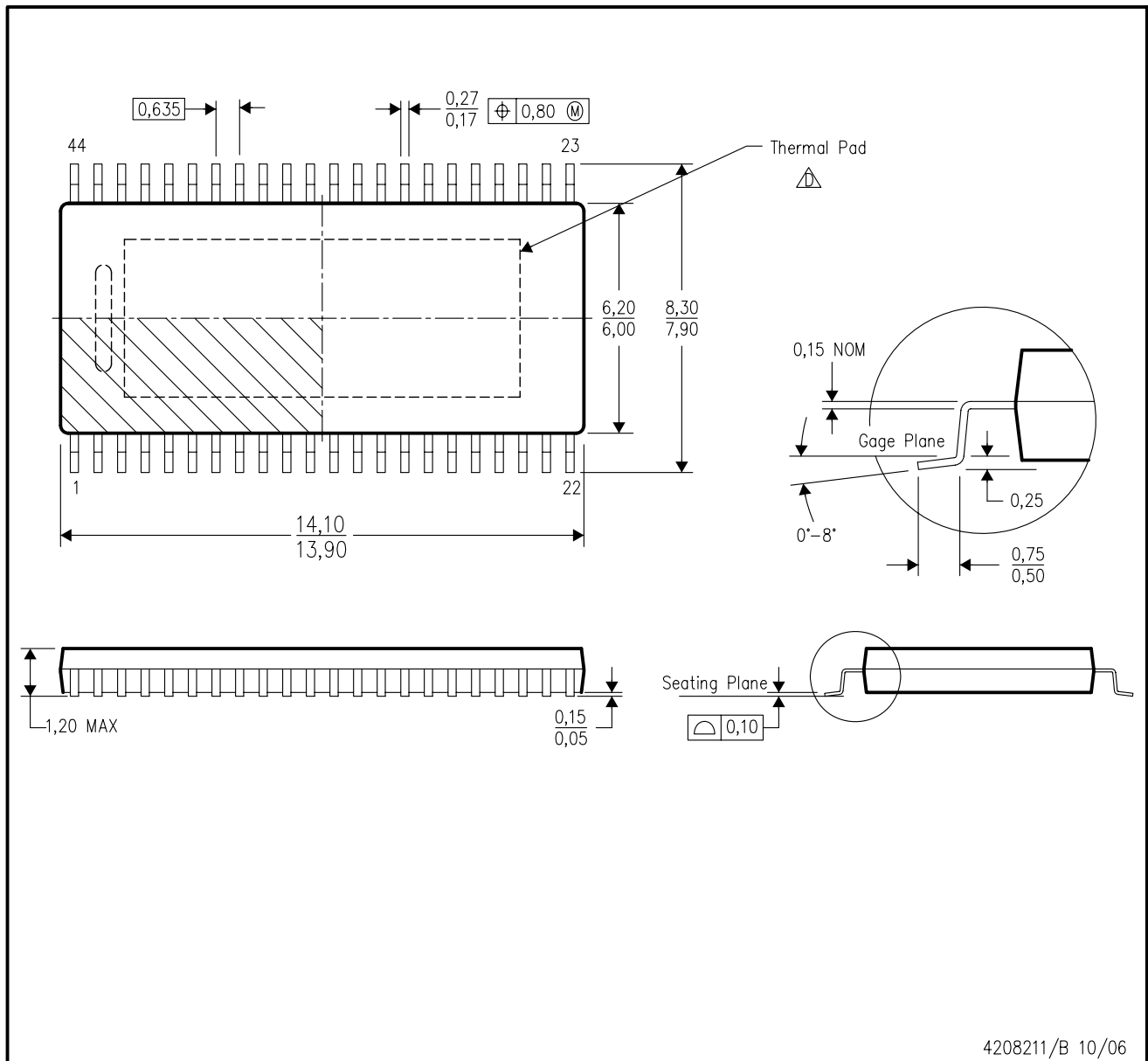


MECHANICAL DATA

DDW (R-PDSO-G44)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE (PAD DOWN)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - △ This package thermal performance is optimized for conductive cooling with attachment to an external heat sink. See the product data sheet for details regarding the exposed thermal pad dimensions.

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